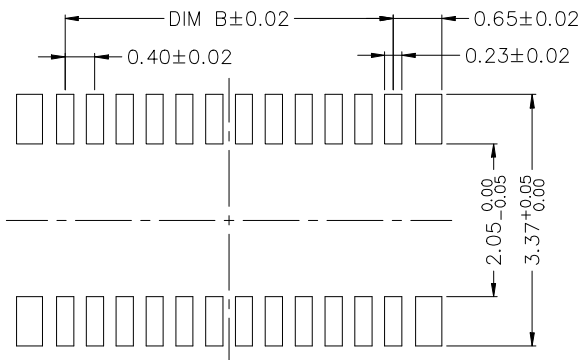
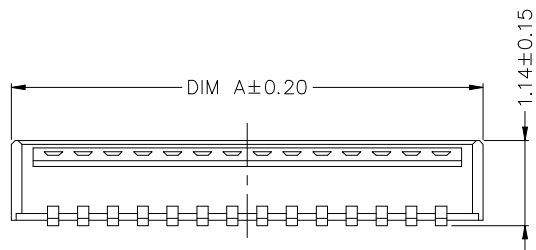
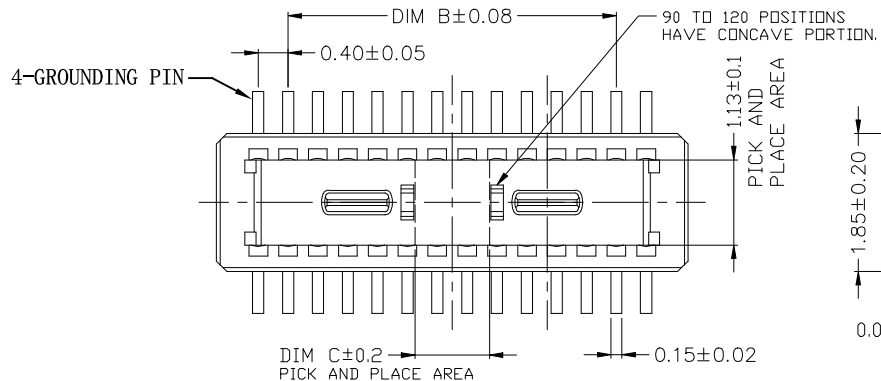
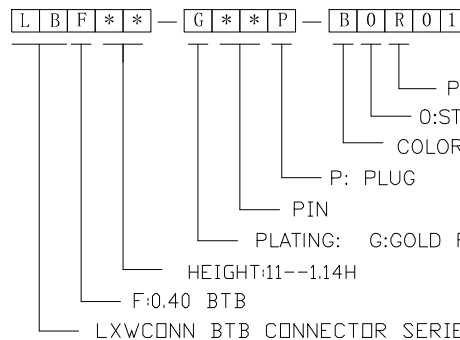
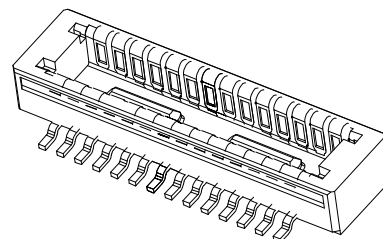
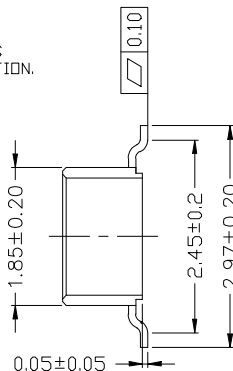




RECOMMENDED PCB LAYOUT



SPECIFICATIONS:

- 1.VOLTAGE/CURRENT RATING: 30V/AC, DC,0.3A;
- 2.WITHSTANDING VOLTAGE: 100V AC/ONE MINUTE;
- 3.INSULATION RESISTANCE: 50M Ω MIN/100V DC.;
- 4.CONTACT RESISTANCE: 90m Ω MAX./1mA,20mV AC,1KHz;
- 5.DURABILITY: 30 CYCLES;
- 6.OPERATING TEMPERATURE RANGE: -35° C TO 85° C.

MATERIAL:

- 1.INSULATOR: LCP UL 94V-0 BLACK;
- 2.TERMINAL: PHOSPHOR BRONZE;

PLATING:

- 1.TERMINAL: CONTACT AREA: GOLD 0.05 μ m"MIN.
SMT LEAD: GOLD 0.025 μ m" MIN.
UNDERPLATING: NICKEL 1 μ m" MIN.

PIN NO.	DIM A	DIM B	DIM C
10	3.52	1.60	1.00
20	5.52	3.60	1.00
24	6.32	4.40	1.20
30	7.52	5.60	1.50
34	8.32	6.40	3.20
40	9.52	7.60	3.20
50	11.52	9.60	3.20
60	13.52	11.60	3.20
70	15.52	13.60	3.20
80	17.52	15.60	3.20
90	19.52	17.60	3.20
100	21.52	19.60	3.20
120	25.52	23.60	3.20

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connectivity LXWCONN ELECTRONICS(SHENZHEN)CO.,LTD

RoHS
Compliant
2013/95/EC



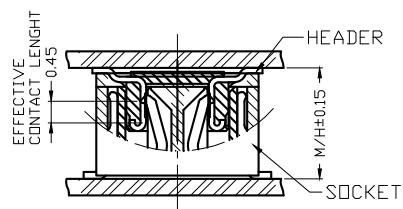
修订 SER	修改摘要 REVISION DESCRIPTION	签名 SIGNATURE	日期 DATE

一般公差
GENERAL TOLERANCE
.X ± 0.3
.XX ± 0.20
.XXX ± 0.10
ANGLES $\pm 1^\circ$

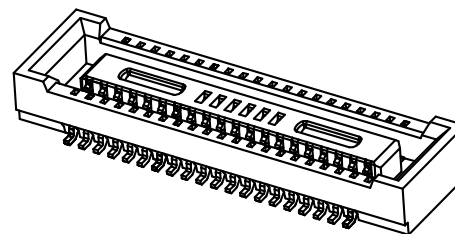
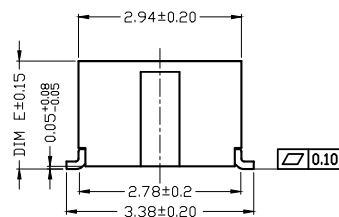


制图(DR): Johnny
2023.07.03
审核(CHKD): Tong
2023.07.03
核准(APPD):

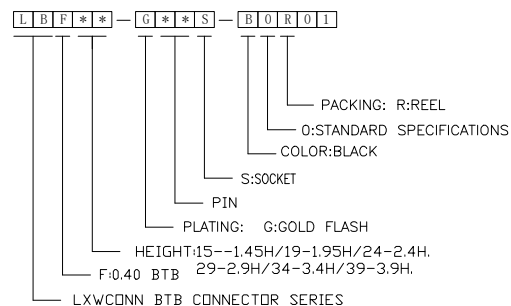
品名(TITLE): BTB HEADER P0.40
料号(PART NO): LBF**-G**P-BOR01
比例(SCALE): 1:1
单位(UNITS): mm
张数(SHEET): 1 OF 1
图幅(SIZE): A4



1. TERMINAL: CONTACT AREA: GOLD 0.05μm" MIN.
SMT LEAD: GOLD 0.025μm" MIN.
UNDERPLATING: NICKEL 1μm" MIN.



PIN NO.	DIM A	DIM B	DIM C	DIM D
10	4.60	1.60	3.55	1.00
20	6.60	3.60	5.55	1.00
24	7.40	4.40	6.35	1.20
30	8.60	5.60	7.55	1.50
34	9.40	6.40	8.35	1.50
40	10.60	7.60	9.55	3.20
50	12.60	9.60	11.55	3.20
60	14.60	11.60	13.55	3.20
70	16.60	13.60	15.55	3.20
80	18.60	15.60	17.55	3.20
90	20.60	17.60	19.55	3.20
100	22.60	19.60	21.55	3.20
120	26.60	23.60	25.55	3.20



M/H	2.00	2.50	3.00	3.50	4.00
DIM E	1.95	2.40	2.90	3.40	3.90

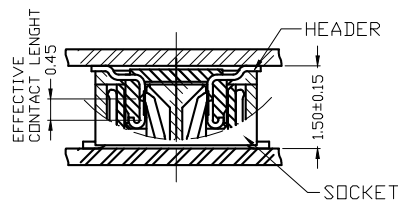


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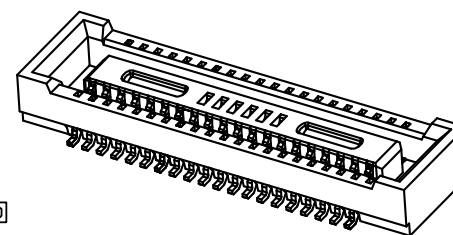
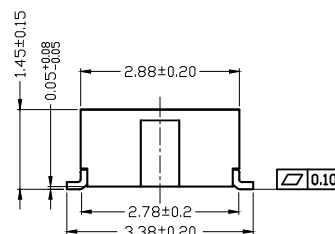
修订 SER	修 改 摘 要 REVISION DESCRIPTION	签 名 SIGNATURE	日期 DATE

一般公差 GENERAL TOLERANCE .X ± 0.3 .XX ± 0.20 .XXX ± 0.10 ANGLES $\pm 1^\circ$	
版本 (REV)	A 

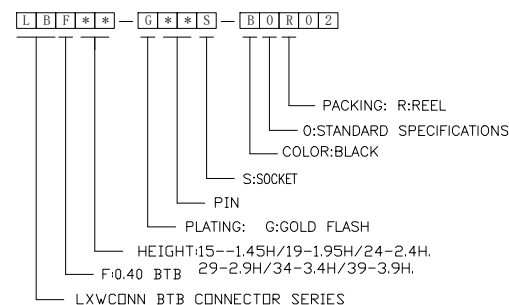
制图 (DR):	Johnny 2023.07.03	品名(TITLE): BTB SCOKET P0.40			
审核 (CHKD):		料号(PART NO): LBF**-G**S-BORO1			
核准 (APPD):	Tong 2023.07.03	比例(SCALE): 1 : 1	单位(UNITS): mm	张数(SHEET): 1 OF 1	图幅(SIZE): A4



1.TERMINAL: CONTACT AREA: GOLD 0.05μm"MIN.
SMT LEAD: GOLD 0.025μm" MIN.
UNDERPLATING: NICKEL 1μm" MIN.



PIN NO.	DIM A	DIM B	DIM C	DIM D
10	4.60	1.60	3.55	1.00
20	6.60	3.60	5.55	1.00
24	7.40	4.40	6.35	1.20
30	8.60	5.60	7.55	1.50
34	9.40	6.40	8.35	1.50
40	10.60	7.60	9.55	3.20
50	12.60	9.60	11.55	3.20
60	14.60	11.60	13.55	3.20
70	16.60	13.60	15.55	3.20
80	18.60	15.60	17.55	3.20
90	20.60	17.60	19.55	3.20
100	22.60	19.60	21.55	3.20
120	26.60	23.60	25.55	3.20



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connectivity LXWCONN ELECTRONICS(SHENZHEN)CO.,LTD

制图 (DR): Johnny 2023.07.03		品名 (TITLE): BTB SCOKET PO. 40 H1. 5			
审核 (CHD):		料号 (PART NO): LBF**-G**S-BOR02			
批准 (APPI): Tong 2023.07.03		比例 (SCALE): 1 : 1	单位 (UNITS): mm	张数 (SHEET): 1 OF 1	图幅 (SIZE): A4